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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Complete if Known

Application Number	Unknown 10/727889
Filing Date	Even Date Herewith 12/4/03
First Named Inventor	Iyer, Ravi
Group Art Unit	Unknown 2815
Examiner Name	Eckert II, George

Sheet 1 of 2

Attorney Docket No: 303.089US4

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JSL Eckert

DATE CONSIDERED 10/22/04

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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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Complete if Known

Application Number	Unknown 10/127,889
Filing Date	Even Date Herewith 12/4/03
First Named Inventor	Iyer, Ravi
Group Art Unit	Unknown 2815
Examiner Name	Eckert II, George

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Attorney Docket No: 303.089US4

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
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